

Title (en)

MULTI-LAYER RELEASE STACK FOR LIGHT INDUCED TRANSFER OF COMPONENTS

Title (de)

MEHRSCHICHTIGER FREISETZUNGSSTAPEL ZUR LICHTINDUZIERTEN ÜBERTRAGUNG VON KOMPONENTEN

Title (fr)

EMPILEMENT DE LIBÉRATION MULTICOUCHE POUR TRANSFERT INDUIT PAR LUMIÈRE DE COMPOSANTS

Publication

EP 4302323 A1 20240110 (EN)

Application

EP 22709835 A 20220301

Priority

- EP 21160226 A 20210302
- NL 2022050114 W 20220301

Abstract (en)

[origin: US2024140081A1] A method and system for light induced transfer of components from a donor substrate to an acceptor substrate are described. The donor substrate includes a transparent carrier configured to carry the components facing the acceptor substrate, and a release stack. The release stack includes a light-absorbing layer, a melt layer, and an adhesive layer. The light-absorbing layer has a relatively high absorption coefficient for absorbing the light beam causing heat which is conducted to the melt layer. The light-absorbing layer has a relatively high melting temperature such that the light-absorbing layer can remain solid while the melt layer is melted. The adhesive layer adheres the components to the melt layer while the melt layer is solid and releases adhesion when the melt layer is melted.

IPC 8 full level

H01L 21/683 (2006.01); **H01L 25/075** (2006.01); **H01L 33/00** (2010.01)

CPC (source: EP US)

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Designated contracting state (EPC)

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DOCDB simple family (application)

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